

## 5-V Dual TTL-to-Differential PECL Translator

### FEATURES

- 1.1-ns (max) Propagation Delay
- Operating Range:  $V_{CC} = 4.2V$  to  $5.7V$  with  $GND = 0 V$
- < 50-ps (typ) Output-to-Output Skew
- Built-In Temperature Compensation
- Drop-In Compatible to the MC10ELT22, MC100ELT22

### APPLICATIONS

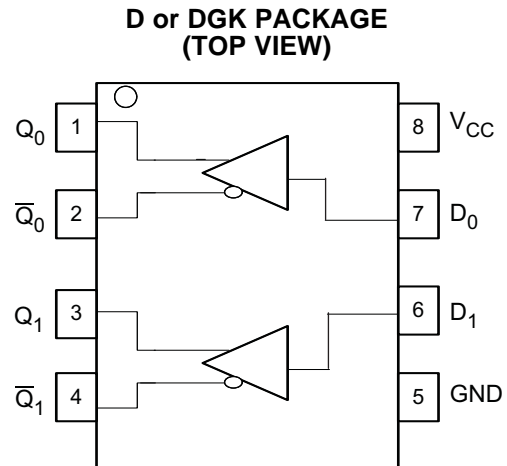
- Data and Clock Transmission Over Backplane
- Signaling Level Conversion for Clock or Data

### DESCRIPTION

The SN65ELT22 is a dual TTL-to-differential PECL translator. It operates on +5-V supply and ground only. The output is undetermined when the inputs are left floating. The low output skew makes the device an ideal solution for clock or data signal translation.

The SN65ELT22 is housed in an industry standard SOIC-8 package and is also available in an optional TSSOP-8 package.

### PIN ASSIGNMENT



**Table 1. Pin Descriptions**

PIN	FUNCTION
$D_0, D_1$	TTL inputs
$Q_0, \bar{Q}_0, Q_1, \bar{Q}_1$	PECL outputs
$V_{CC}$	Positive supply
GND	Ground

### ORDERING INFORMATION<sup>(1)</sup>

PART NUMBER	PART MARKING	PACKAGE	LEAD FINISH
SN65ELT22D	SN65ELT22	SOIC	NiPdAu
SN65ELT22DGK	SN65ELT22	SOIC-TSSOP	NiPdAu

(1) Leaded device options are not initially available; contact a sales representative for further details



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

PARAMETER	CONDITIONS	VALUE	UNIT
Absolute PECL mode supply voltage, $V_{CC}$	GND = 0 V	6	V
Input voltage, $V_{IN}$	GND = 0 V	$GND + 0.025 < V_{IN} < V_{CC} - 0.025$	V
Output current	Continuous	50	mA
	Surge	100	
Operating temperature range		–40 to 85	°C
Storage temperature range		–65 to 150	°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	POWER RATING $T_A < 25^\circ\text{C}$ (mW)	THERMAL RESISTANCE, JUNCTION-TO-AMBIENT NO AIRFLOW	DERATING FACTOR $T_A > 25^\circ\text{C}$ (mW/°C)	POWER RATING $T_A = 85^\circ\text{C}$ (mW)
SOIC	Low-K	719	139	7	288
	High-K	840	119	8	336
SOIC-TSSOP	Low-K	469	213	5	188
	High-K	527	189	5	211

## THERMAL CHARACTERISTICS

PARAMETER		MIN	TYP	MAX	UNIT
$\theta_{JB}$	Junction-to-board thermal resistance	SOIC	79		°C/W
		SOIC-TSSOP	120		
$\theta_{JC}$	Junction-to-case thermal resistance	SOIC	98		°C/W
		SOIC-TSSOP	74		

## KEY ATTRIBUTES

CHARACTERISTICS	VALUE	
Moisture sensitivity level	Level 1	
Flammability rating (oxygen index: 28 to 34)	UL 94 V-0 at 0.125 in	
Electrostatic discharge	Human body model	4 kV
	Charge device model	2 kV
	Machine model	200 V
Meets or exceeds JEDEC Spec EIA/JESD78 latchup test		

## PECL DC CHARACTERISTICS

 At  $V_{CC} = 5.0\text{ V}$ ,  $GND = 0.0\text{ V}$  (unless otherwise noted)<sup>(1)(2)</sup>

PARAMETER	TEST CONDITIONS	$T_A = -40^\circ\text{C}$			$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$			UNIT	
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		
$I_{CC}$	Power supply current		17.3	20		18.2	20		19.4	22	mA	
$V_{OH}$	High-level output voltage	See <sup>(3)</sup>	3915	3954	4120	3915	3958	4120	3915	3961	4120	mV
$V_{OL}$	Low-level output voltage	See <sup>(3)</sup>	3170	3236	3380	3170	3231	3380	3170	3229	3380	mV

- (1) The device meets the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary  $+0.7\text{ V}/-0.8\text{ V}$ .
- (3) Outputs are terminated through a 50- $\Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

## TTL DC CHARACTERISTICS

 At  $V_{CC} = 4.2\text{ V}$  to  $5.7\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  (unless otherwise noted)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{IH}$	High-level input current $V_{IN} = 2.7\text{ V}$ , $V_{IN} = (V_{CC} - 0.025)\text{ V}$			20	$\mu\text{A}$
$I_{IHH}$	High-level input current $V_{IN} = V_{CC}$			20	$\mu\text{A}$
$I_{IL}$	Low-level input current $V_{IN} = 0.5\text{ V}$ , $V_{IN} = (GND + 0.025)\text{ V}$			-200	$\mu\text{A}$
$V_{IK}$	Input clamp diode voltage $I_{IN} = -18\text{ mA}$			-1.2	V
$V_{IH}$	High-level input voltage	2.0	$V_{CC} - 0.025$		V
$V_{IL}$	Low-level input voltage	$GND + 0.025$		0.8	V

- (1) The device meets the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

## AC CHARACTERISTICS

 At  $V_{CC} = 4.2\text{ V}$  to  $5.7\text{ V}$ ,  $GND = 0.0\text{ V}$  (unless otherwise noted)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A = -40^\circ\text{C}$			$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
$f_{MAX}$	Max switching frequency <sup>(2)</sup> , see Figure 5		500			490			470		MHz
$t_{PLH}$	Propagation delay time 1.5 V to 50%	0.6	0.83	1.1	0.6	0.84	1.1	0.6	0.85	1.1	ns
$t_{PHL}$		0.5		0.9	0.5		0.9	0.5		0.9	
$t_{SKEW}$	Within device skew	See <sup>(3)</sup>	25	90	25	90	25	90	25	90	ps
	Device-to-device skew	See <sup>(4)</sup>	25	100	25	100	25	100	25	100	
$t_{JITTER}$	Random clock jitter (RMS)			0.5		0.5			0.5		ps
$t_r/t_f$	Output rise/fall times	Q (20%–80%)	0.7	1.1	0.7	1.1	0.7	1.1	0.7	1.1	ns

- (1) The device meets the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) Maximum switching frequency measured at output amplitude of 300 mV<sub>pp</sub>.
- (3) Measured between outputs under the identical transitions and conditions on any one device.
- (4) Device-to-device skew for identical transitions at identical  $V_{CC}$  levels.

Typical Termination for Output Driver

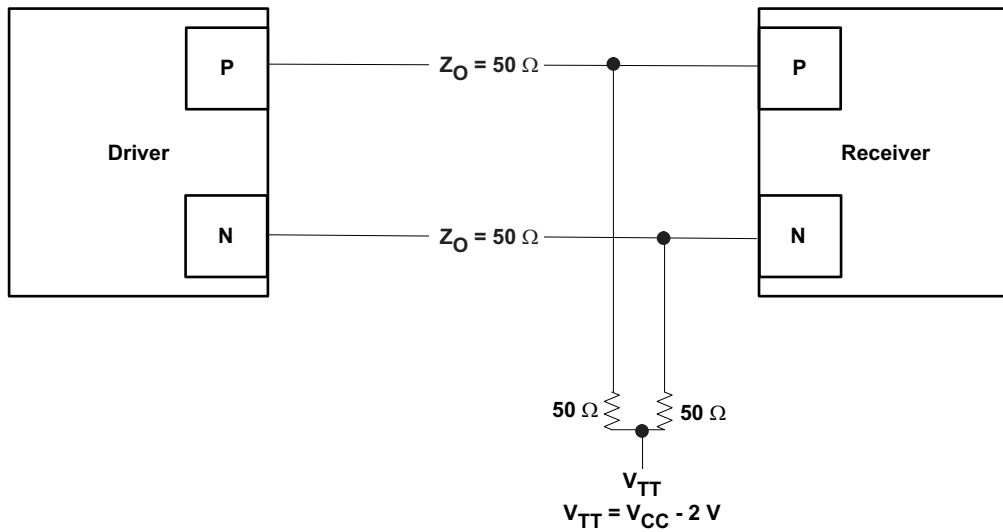


Figure 1. Typical Termination for Driver

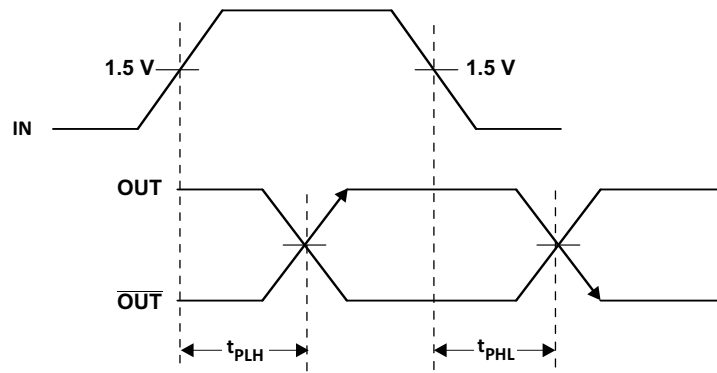


Figure 2. Output Propagation Delay



Figure 3. Output Rise and Fall Times

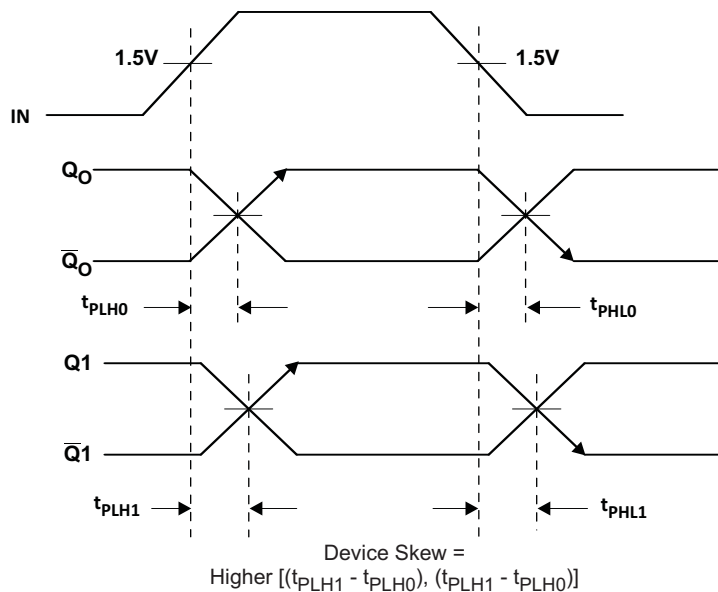


Figure 4. Device Skew

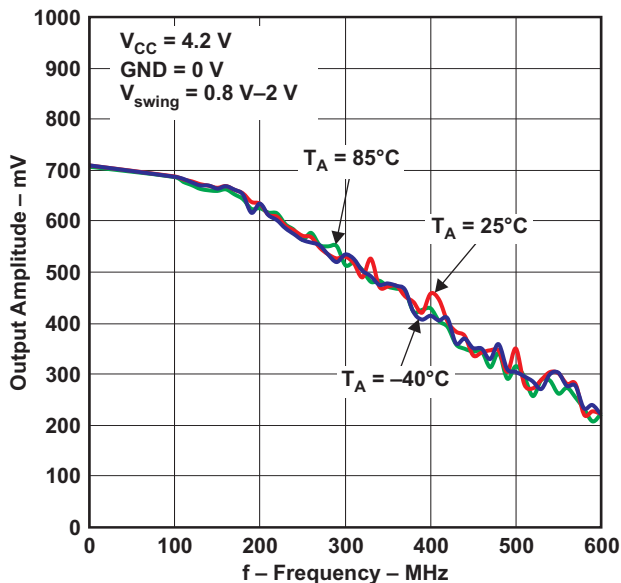


Figure 5. Output Amplitude vs. Frequency

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN65ELT22D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65ELT22DGK	ACTIVE	VSSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65ELT22DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65ELT22DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ELT22DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
SN65ELT22DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65ELT22DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
SN65ELT22DR	SOIC	D	8	2500	367.0	367.0	35.0





D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

**TI E2E Community** [e2e.ti.com](http://e2e.ti.com)